



Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D T _A = +25 ℃
60V	$66m\Omega @ V_{GS} = 10V$	5.0A
	$97m\Omega @ V_{GS} = 4.5V$	4.1A

Description and Applications

This MOSFET is designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

Features and Benefits

- Low on-resistance
- Fast switching speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

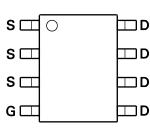
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020

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- Terminals Connections: See Diagram Below
- Terminals: Finish Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 3
- Weight: 0.074 grams (Approximate)



Top View



Top View





S

D

Ordering Information (Notes 4 & 5)

Part Number	Compliance	Case	Packaging
DMN6066SSS-13	Commercial	SO-8	2,500/Tape & Reel
DMN6066SSSQ-13	Automotive	SO-8	2,500/Tape & Reel

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

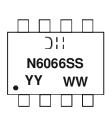
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_grade_definitions/.

5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:



SO-8

):! = Manufacturer's Marking
 N6066SS = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Year (ex: 09 = 2009)
 WW = Week (01 - 53)



Maximum Ratings (@T_A = +25 °C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	60	V
Gate-Source Voltage		(Note 6)	V _{GS}	±20	V
Single Pulsed Avalanche En	ergy	(Note 11)	E _{AS}	37.5	mJ
Single Pulsed Avalanche Cu	irrent	(Note 11)	I _{AS}	5.0	А
Continuous Drain Current V _{GS} = 10V		(Note 8)	ID	5.0	
	$V_{GS} = 10V$	/ T _A = +70 ℃ (Note 8)		4.0	А
		(Note 7)		3.7	
Pulsed Drain Current	$V_{GS} = 10V$	(Note 9)	IDM	23	А
Continuous Source Current	(Body diode)	(Note 8)	I _S	4.0	А
Pulsed Source Current (Bod	y diode)	(Note 9)	I _{SM}	23	А

Thermal Characteristics (@T_A = +25 $^{\circ}$ C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Power Dissipation Linear Derating Factor	(Note 7)		1.56 12.5	W	
	(Note 8)	— P _D	2.81 22.5	mW/℃	
Thermal Resistance, Junction to Ambient	(Note 7) (Note 8)	— R _{θJA}	80.0 44.5	°C/W	
Thermal Resistance, Junction to Lead	(Note 10)	R _{θJL}	37.0	1	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to 150	°C	

Notes:

6. AEC-Q101 V_{GS} maximum is ±16V.
7. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

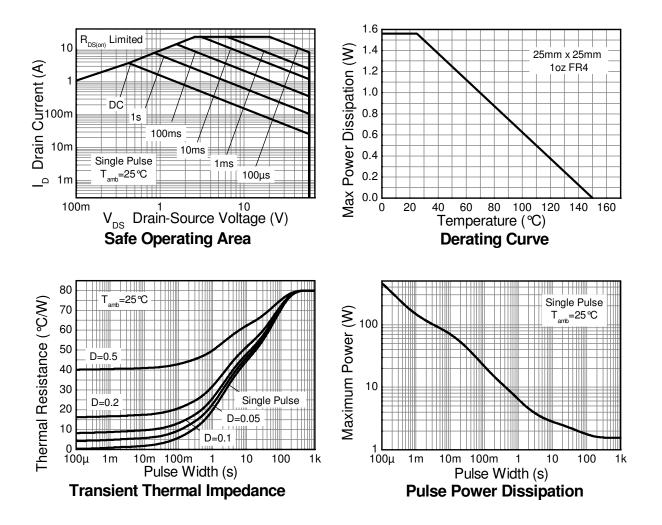
8. Same as note (7), except the device is measured at t ≤ 10 sec.
9. Same as note (7), except the device is pulsed with D= 0.02 and pulse width 300 μs. The pulse current is limited by the maximum junction temperature.

10. Thermal resistance from junction to solder-point (at the end of the drain lead).

11. UIS in production with L = 3.0mH, I_{AS} = 5.0Å, R_G = 25 Ω , V_{DD} =50V, starting T_J = +25 °C.



Thermal Characteristics





Electrical Characteristics (@T_A = +25 °C, unless otherwise specified.)

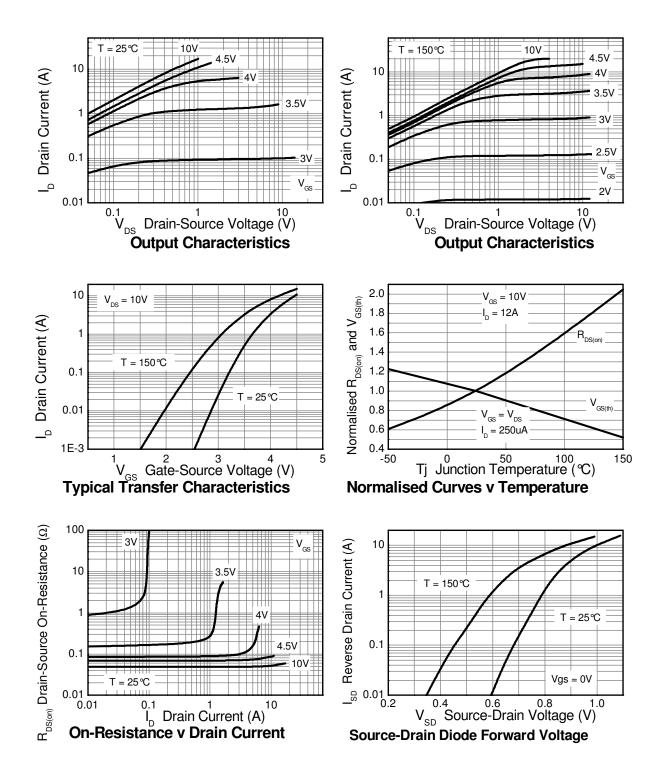
Characteristic	Symbol	Min	Тур	Max	Unit	Test	Condition
OFF CHARACTERISTICS			•				
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	$I_{D} = 250 \mu A, V_{GS} = 0V$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	0.5	μA	$V_{DS} = 60V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}		_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(th)}	1.0	_	3.0	V	$I_D = 250 \mu A$, $V_{DS} = V_{GS}$	
Statia Drain Source On Registeres (Note 10)	Б		0.048	0.066	0	$V_{GS} = 10V, I_D$	= 4.5A
Static Drain-Source On-Resistance (Note 12)	R _{DS} (ON)	_	0.068	0.097	Ω	$V_{GS} = 4.5V, I_D = 3.5A$	
Forward Transconductance (Notes 12 & 13)	g fs	_	19.2	_	S	V _{DS} = 15V, I _D = 6A	
Diode Forward Voltage (Note 12)	V _{SD}	_	0.89	1.15	V	$I_{S} = 4.5A, V_{GS} = 0V$	
Reverse Recovery Time (Note 13)	t _{rr}		23	_	ns	-I _S = 2.4A, di/dt = 100A/μs	
Reverse Recovery Charge (Note 13)	Qrr		19.7	_	nC		
DYNAMIC CHARACTERISTICS (Note 13)							
Input Capacitance	Ciss	—	502	_	рF	V _{DS} = 30V, V _{GS} = 0V – f = 1MHz	
Output Capacitance	C _{oss}	_	45.7	_	pF		
Reverse Transfer Capacitance	Crss		27.1	_	pF		
Total Gate Charge (Note 14)	Qg		5.4	_	nC	$V_{GS} = 4.5V$	
Total Gate Charge (Note 14)	Qg	_	10.3	_	nC	V _{DS} = 30V	
Gate-Source Charge (Note 14)	Q _{gs}	_	1.7	_	nC	$V_{GS} = 10V$	$I_D = 4.5A$
Gate-Drain Charge (Note 14)	Q _{gd}	_	3.2		nC		
Turn-On Delay Time (Note 14)	t _{D(on)}	_	2.7		ns	$V_{DD} = 30V, V_{GS} = 10V$ $I_D = 1A, R_G \cong 6.0\Omega$	
Turn-On Rise Time (Note 14)	tr	_	2.4		ns		
Turn-Off Delay Time (Note 14)	t _{D(off)}	_	14.7		ns		
Turn-Off Fall Time (Note 14)	t _f		5.4		ns		

Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%.
 For design aid only, not subject to production testing.
 Switching characteristics are independent of operating junction temperatures.

Notes:

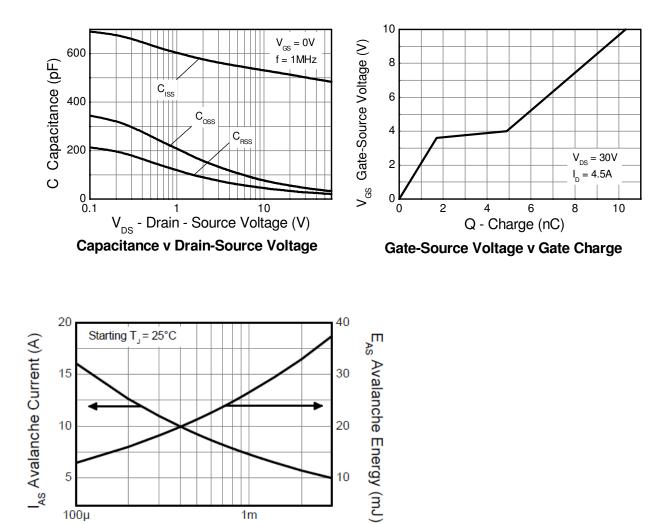


Typical Characteristics





Typical Characteristics (continued)



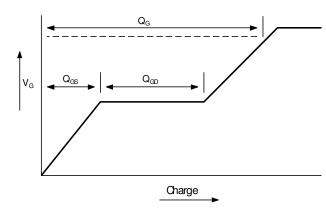
1m

L Inductor (H) Single-Pulsed Avalanche Rating

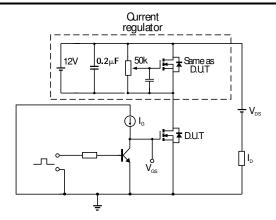
10<mark>0µ</mark>



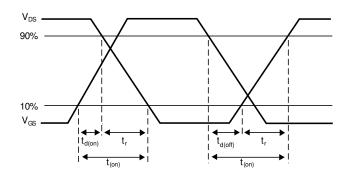
Test Circuits



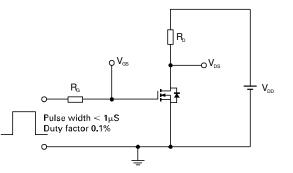
Basic gate charge waveform



Gate charge test circuit



Switching time waveforms

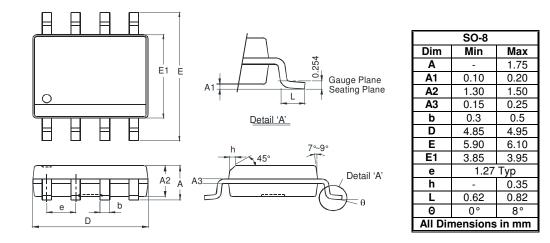


Switching time test circuit



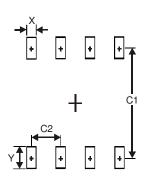
Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1.27



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